SDAS016A - MARCH 1984 - REVISED MAY 1986

- Package Options Include Plastic Small Outline Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs
- Dependable Texas Instruments Quality and Reliability

description

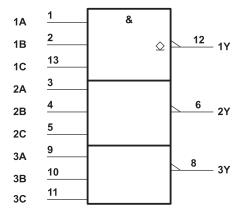
These devices contain three independent 3-input AND gates with open-collector outputs. These gates perform the Boolean functions $Y = A \bullet B \bullet C$ or $Y = \overline{A + B + C}$ in positive logic. The open-collector outputs require pullup resistors to perform correctly. They may be connected to other open-collector outputs to implement active-low wired-OR or active-high wired-AND functions. Open-collector devices are often used to generate higher V_{OH} levels.

The SN54ALS15A is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74ALS15A is characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each gate)

	NPUTS	OUTPUT	
Α	В	С	Υ
Н	Н	Н	Н
L	Χ	Χ	L
Х	L	X	L
Х	Χ	L	L

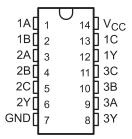
logic symbol†



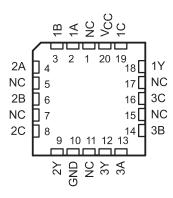
[†] This symbol is in accordance with ANS/EEE Std 91-1984 and IEC Publication 617-12

Pin numbers shown are for D, J, and N packages.

SN54ALS15A...J PACKAGE SN74ALS15...D OR N PACKAGE (TOP VIEW)

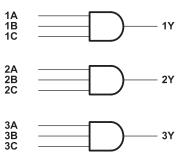


SN54ALS15A ... FK PACKAGE (TOP VIEW)



NC - No internal connection

logic diagram (positive logic)





1

SN54ALS15A, SN74ALS15A TRIPLE 3-INPUT POSITIVE-AND GATES WITH OPEN-COLLECTOR OUTPUTSWITH OPEN-COLLECTOR OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC}	7 V
Input voltage	7 V
Operating free-air temperature range: SN54ALS15A	- 55°C to 125°C
SN74ALS15A	0°C to 70°C
Storage temperature range	-65°C to 150°C

recommended operating conditions

		SN54ALS15A		SN74ALS15A			UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
\vee_{IL}	Low-level input voltage			0.7			8.0	V
Vон	High-level output voltage			5.5			5.5	V
loL	Low-level output current			4			8	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SI	SN54ALS15A			SN74ALS15A		
PARAMETER			MIN	TYP [†]	MAX	MIN	TYP†	MAX	UNIT
VIK	V _{CC} = 4.5 V,	I I = −18 mA			-1.5			-1.5	V
\/a.	$V_{CC} = 4.5 \text{ V},$	I _{OL} = 4 mA		0.25	0.4		0.25	0.4	V
V _{OL}	V _{CC} = 4.5 V,	I _{OL} = 8 mA					0.35	0.5	V
Гон	V _{CC} = 4.5 V,	V _{OH} = 5.5 mA			0.1			0.1	mA
II	V _{CC} = 5.5 V,	V _I = 7 ∨			0.1			0.1	mA
lіН	$V_{CC} = 5.5 V$,	V _I = 2.7 V			20			20	μΑ
I _{IL}	V _{CC} = 5.5 V,	V _I = 0.4V			-0.1			-0.1	mA
Іссн	V _{CC} = 5.5 V,	V _I = 4.5 V		1	1.8		1	1.8	mA
ICCL	$V_{CC} = 5.5 V$,	∨ = 0 ∨		1.66	3		1.66	3	mA

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C

switching characteristics (see Note 1)

PARAMETER	FROM (INPUT)	ТО (ОИТРИТ)	C R	V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R_L = 50 Ω , T_A = MIN to MAX			UNIT
			SN54A	SN54ALS15A		LS15A	
			MIN	MAX	MIN	MAX	
^t PLH	Any	Y	20	59	20	45	ns
^t PHL	Any	Y	6	25	6	20	ns

NOTE 1: Load circuit and voltage waveforms are shown in Section 1 of ALS/AS Logic Data Book, 1986.





PACKAGE OPTION ADDENDUM

18-Sep-2008

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ALS15AD	OBSOLETE	SOIC	D	14	TBD	Call TI	Call TI
SN74ALS15ADR	OBSOLETE	SOIC	D	14	TBD	Call TI	Call TI
SN74ALS15AN	OBSOLETE	PDIP	N	14	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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